



# TG-N8000 Putty

## Non-silicone Thermal Putty

REACH Compliant

RoHS Compliant

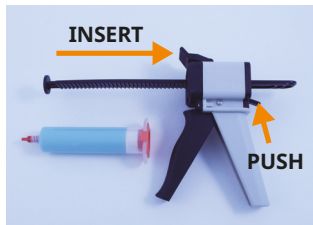
### Features

- Silicone free thermal gel
- Lower contact thermal impedance than thermal pads
- Physical property in between liquid and solid state
- Gap fillers for uneven or irregular surfaces of heat sources and heat sink
- Applicable for dispenser

### Application:

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

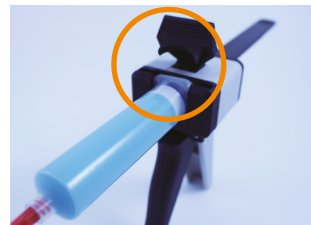
### Operation Manual



① Push the latch and insert the stick.



② Put the tube in and twist.



③ Close the cover.

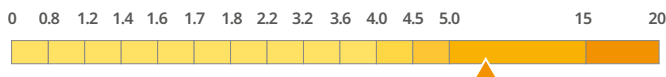


④ Take off the plug.

(The putty in the picture does not represent the actual product.)

### Properties

**Thermal Conductivity : 8.0 W/mK**



Properties	Unit	TG-N8000 Putty	Tolerance	Test Method
Thermal Conductivity	W/m·K	8.0	-	ASTM D5470 Modified
Color	-	Yellow	-	-
Viscosity	Pa·s	430	± 100	Brookfield
Density	g/cm <sup>3</sup>	3	± 0.15	ASTM D792
Volume Resistivity	Ohm·m	>10 <sup>10</sup>	-	ASTM D257
Operating Temperature	°C	-40~+125	-	-
Standard Package	-	Tube/ Pot	-	-